

## LVDS Interface ICs

# 35bit LVDS Transmitter

## 35:5 Serializer


**BU8254GUW**

No.13057EBT10

**●Description**

LVDS Interface IC of ROHM "Serializer" "Deserializer" operate from 8MHz to 150MHz wide clock range, and number of bits range is from 35 to 70. Data is transmitted seven times (7X) stream and reduce cable number by 3(1/3) or less. The ROHM's LVDS has low swing mode to be able to expect further low EMI.

**●Features**

- 1) 35bits data of parallel LVCMOS level inputs are converted to five channels of LVDS data stream.
- 2) 30bits of RGB data and 5bits of timing and control data(HSYNC, VSYNC, DE, CNTL1, CNTL2) are transmitted up to 784Mbps effective rate per LVDS channel.
- 3) Support clock frequency from 8MHz up to 112MHz.
- 4) Support consumer video format including 480i, 480P, 720P and 1080i as well.
- 5) Clock edge selectable
- 6) Power down mode
- 7) Support spread spectrum clock generator.
- 8) Support reduced swing LVDS for low EMI.
- 9) 30bit LVDS receiver is recommended to use BU90R104.

**●Applications**

Flat Panel Display

**●Precaution**

- This chip is not designed to protect from radioactivity.
- The chip is made strictly for the specific application or equipment.  
Then it is necessary that the unit is measured as need.
- This document may be used as strategic technical data which subjects to COCOM regulations.

●Block Diagram

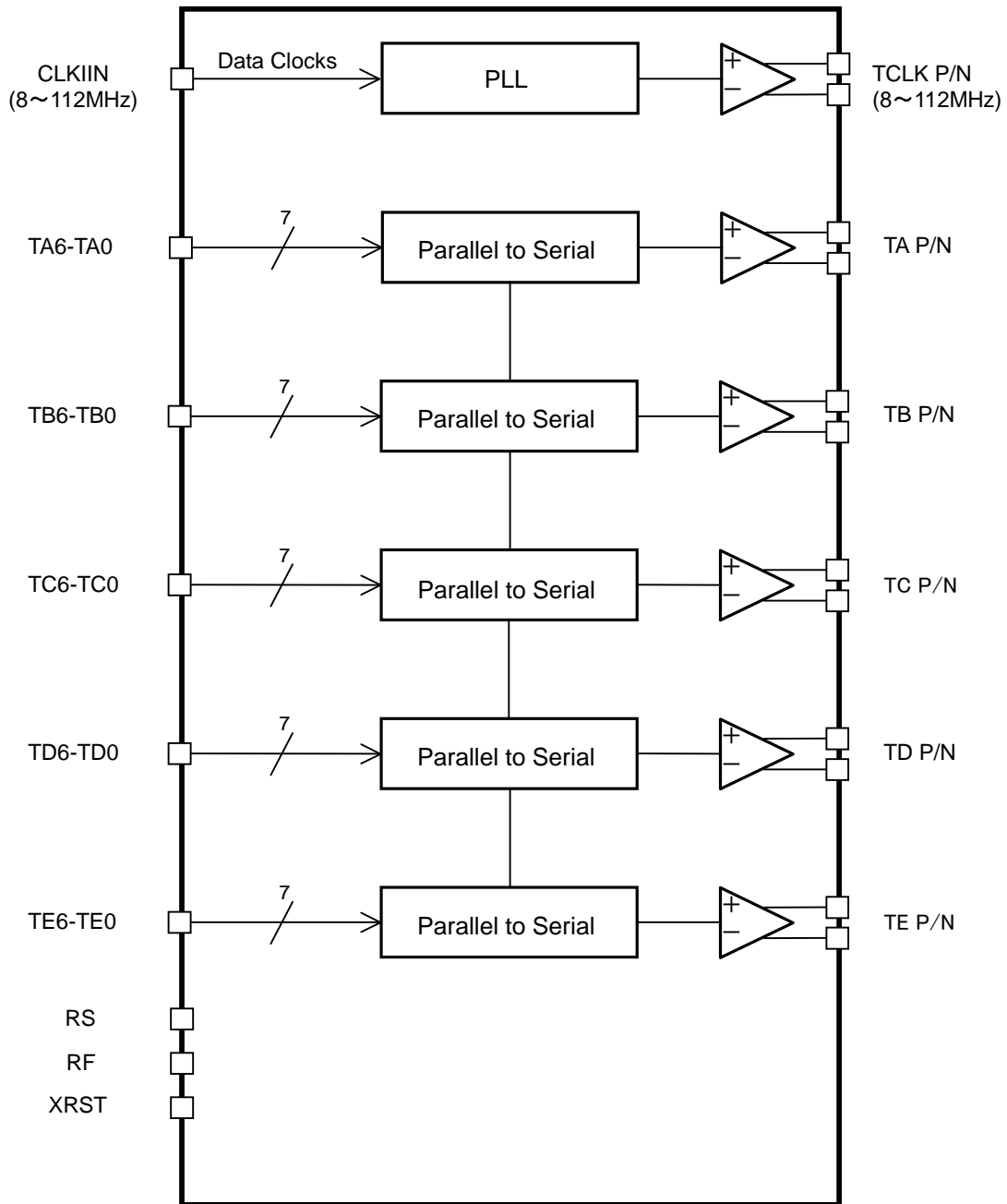


Fig.1 Block Diagram

●VBGA099W060 Package Outline and Specification

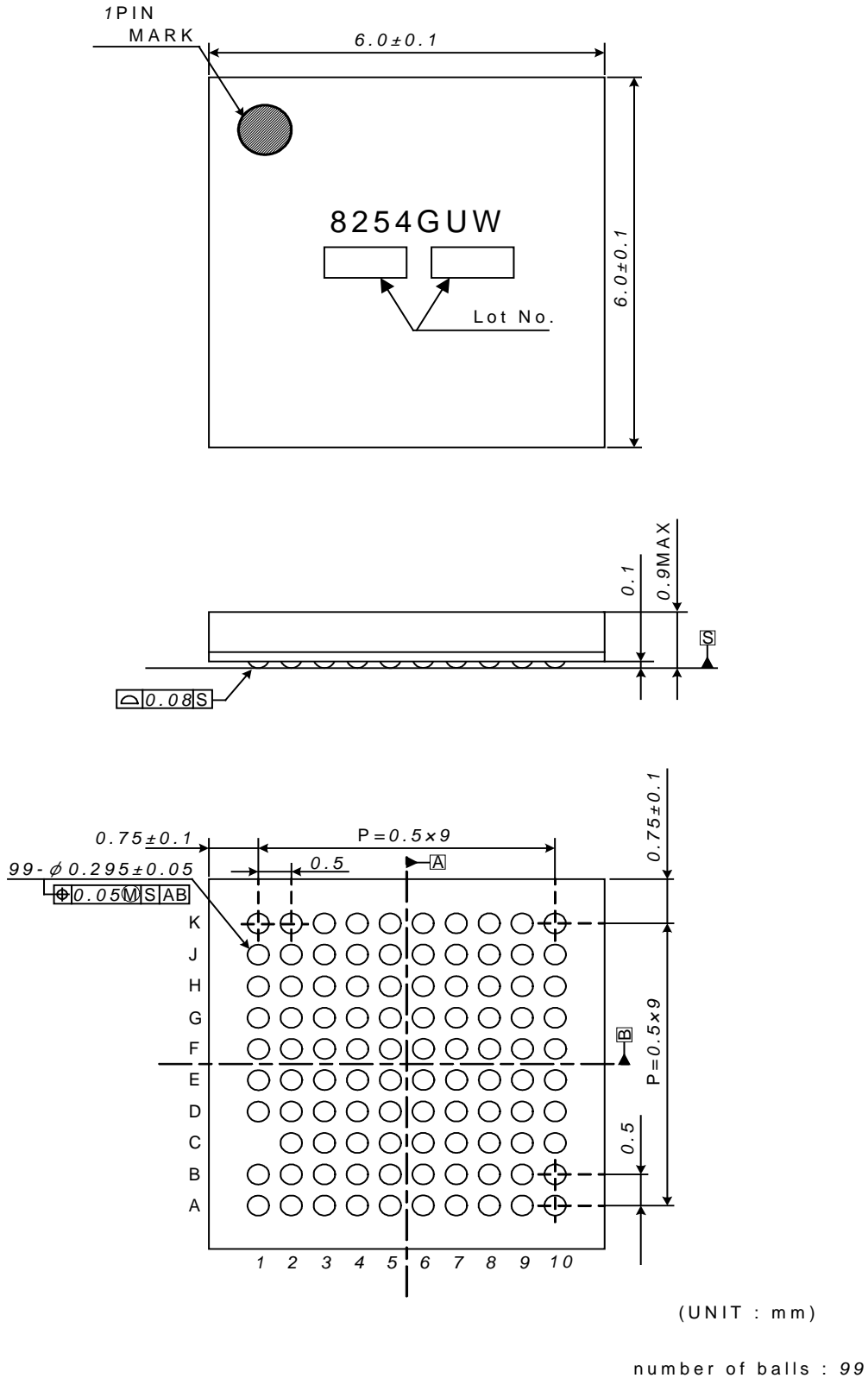


Fig.2 VBGA099W060 Package Outline and Specification

●Pin configuration

	1	2	3	4	5	6	7	8	9	10
A	(NC)	TAN	TAP	TBP	TCN	TCLKN	TDN	TEN	(NC)	(NC)
B	(NC)	(NC)	TBN	LVDSVDD	TCP	TCLKP	TDP	TEP	(NC)	(NC)
C	(1PIN)	(NC)	LVDSGND	LVDSGND	(NC)	(NC)	LVDSGND	(NC)	PLLVD	PLLGND
D	TA5	TA1	TA0	TA2	(NC)	(NC)	TE6	(NC)	(NC)	(NC)
E	TB0	TA4	TA3	GND	TA6	(NC)	XRST	TE5	GND	CLK_IN
F	TB2	TB1	RS	TB3	(NC)	TE3	VDD	TE1	TE2	TE4
G	TB4	(NC)	GND	TB5	(NC)	(NC)	TE0	(NC)	GND	TD6
H	(NC)	(NC)	(NC)	(NC)	TC4	(NC)	(NC)	(NC)	(NC)	TD5
J	(NC)	TB6	VDD	TC2	GND	TC6	RF	TD2	TD4	(NC)
K	(NC)	TC0	TC1	TC3	TC5	TD0	TD1	TD3	(NC)	(NC)

Fig.3 Pin Diagram (Top View)

## ● Pin Description

Table 1 : Pin Description

Pin Name	Pin No.	Type	Descriptions		
TAP, TAN	A3,A2	LVDS OUT	LVDS data out.		
TBP, TBN	A4,B3	LVDS OUT			
TCP, TCN	B5,A5	LVDS OUT			
TDP, TDN	B7,A7	LVDS OUT			
TEP, TEN	B8,A8	LVDS OUT			
TCLKP, TCLKN	B6,A6	LVDS OUT		LVDS clock out.	
TA0~TA6	D3,D2,D4,E3,E2,D1,E5	IN	Pixel data inputs.		
TB0~TB6	E1,F2,F1,F4,G1,G4,J2	IN			
TC0~TC6	K2,K3,J4,K4,H5,K5,J6	IN			
TD0~TD6	K6,K7,J8,K8,J9,H10,G10	IN			
TE0~TE6	G7,F8,F9,F6,F10,E8,D7	IN			
XRST	E7	IN		H : Normal operation, L : Power down (all outputs are Hi-Z)	
RS	F3	IN	LVDS swing mode, $V_{REF}$ <sup>*1</sup> select.		
			RS	LVDS Swing	Small Swing Input Support
			$V_{DD}$	350mV	N/A
			0.6~1.4V	350mV	RS- $V_{REF}$
			GND	200mV	N/A
			<sup>*1</sup> $V_{REF}$ is Input Reference Voltage.		
RF	J7	IN	Input clock triggering edge select. H : Rising edge, L : Falling edge.		
VDD	F7,J3	Power	Power supply pins for LVCMOS inputs and digital core.		
CLKIN	E10	IN	Clock input.		
GND	E4,E9,G3,G9,J5	Ground	Ground pins for LVCMOS inputs and digital core.		
LVDS VDD	B4	Power	Power supply pins for LVDS outputs.		
LVDS GND	C3,C4,C7	Ground	Ground pins for LVDS outputs.		
PLLVD	C9	Power	Power supply pin for PLL core.		
PLLGND	C10	Ground	Ground pins for PLL core.		

## ●Electrical characteristics

### ■Rating

Table 2 : Absolute Maximum Rating

Parameter	Symbol	Rating		Units
		Min	Max	
Supply Voltage	V <sub>DD</sub>	-0.3	4.0	V
Input Voltage	V <sub>IN</sub>	-0.3	V <sub>DD</sub> +0.3	V
Output Voltage	V <sub>OUT</sub>	-0.3	V <sub>DD</sub> +0.3	V
Storage Temperature Range	T <sub>stg</sub>	-55	125	°C

Table 3 : Package Power

PACKAGE	Power Dissipation (mW)	De-rating (mW/°C) <sup>*1</sup>
VBGA099W060	380	3.8
	880 <sup>*2</sup>	8.8 <sup>*2</sup>

\*1: At temperature Ta >25°C

\*2: Package power when mounting on the PCB board.

The size of PCB board :70 × 70 × 1.6(mm<sup>3</sup>)

The material of PCB board :The FR4 glass epoxy board.(3% or less copper foil area)

(It is recommended to apply the above package power requirement to PCB board when the small swing input mode is used)

Table 4 : Recommended Operating Conditions

Parameter	Symbol	Rating			Units	Conditions
		Min	Typ	Max		
Supply Voltage	V <sub>DD</sub>	3.0	3.3	3.6	V	VDD,LVDSVDD,PLLVD
Operating Temperature Range	Topr	-20	-	85	°C	Clock frequency from 8MHz up to 90MHz
		0	-	70	°C	Cock frequency from 90MHz up to 112MHz

### ■ DC characteristics

Table 5 : LVCMOS DC Specifications( $V_{DD}=3.0V\sim 3.6V$ ,  $T_a=-20^{\circ}C\sim 85^{\circ}C$ )

Parameter	Symbol	Rating			Units	Conditions
		Min	Typ	Max		
High Level Input Voltage	$V_{IH}$	$V_{DD} \times 0.8$	-	$V_{DD}$	V	exclude RS pin
Low Level Input Voltage	$V_{IL}$	GND	-	$V_{DD} \times 0.2$	V	
High Level Input Voltage	$V_{IHRS}$	$V_{DD} \times 0.8$	-	$V_{DD}$		RS pin
Low Level Input Voltage	$V_{ILRS}$	GND	-	0.2		
Small Swing Voltage	$V_{DDQ}^{*1}$	1.2	-	2.8	V	
Input Reference Voltage	$V_{REF}$	-	$V_{DDQ}/2$	-	-	Small Swing( $RS=V_{DDQ}/2$ )
Small Swing High Level Input Voltage	$V_{SH}^{*2}$	$V_{DDQ}/2 + 200mV$	-	-	V	$V_{REF}=V_{DDQ}/2$
Small Swing Low Level Input Voltage	$V_{SL}^{*2}$	-	-	$V_{DDQ}/2 - 200mV$	V	$V_{REF}=V_{DDQ}/2$
Input Current	$I_{INC}$	-10	-	+10	$\mu A$	$0V \leq V_{IN} \leq V_{DD}$

\*1:  $V_{DDQ}$  voltage defines max voltage of small swing input. It is not an actual input voltage.

\*2: Small swing signal is applied to TA[6:0], TB[6:0], TC[6:0], TD[6:0] TE[6:0], CLKIN.

Table 6 : LVDS Transmitter DC Specifications( $V_{DD}=3.0V\sim 3.6V$ ,  $T_a=-20^{\circ}C\sim 85^{\circ}C$ )

Parameter	Symbol	Rating			Units	Conditions	
		Min	Min	Min		$RL=100\Omega$	
Differential Output Voltage	$V_{OD}$	250	350	450	mV		
		100	200	300	mV	Reduced swing $RS=GND$	
Change in VOD between complementary output states	$\Delta V_{OD}$	-	-	35	mV	$RL=100\Omega$	
Common Mode Voltage	$V_{OC}$	1.125	1.25	1.375	V		
Change in VOC between complementary output states	$\Delta V_{OC}$	-	-	35	mV		
Output Short Circuit Current	$I_{OS}$	-	-	-24	mA	$V_{OUT}=0V$ , $RL=100\Omega$	
Output TRI-STATE Current	$I_{OZ}$	-10	-	+10	$\mu A$	$XRST=0V$ , $V_{OUT}=0V$ to $V_{DD}$	

### ■ Supply Current

Table 7 : Supply Current

Parameter	Symbol	Rating			Units	Conditions	
		Min	Typ	Max			
Transmitter Supply Current	I <sub>TCCG</sub>	-	57	-	mA	RL=100Ω,CL=5pF V <sub>DD</sub> =3.3V,RS=V <sub>DD</sub> Gray Scale Pattern	f=85MHz
		-	42	-	mA	RL=100Ω,CL=5pF V <sub>DD</sub> =3.3V,RS=GND Gray Scale Pattern	f=85MHz
Transmitter Supply Current	I <sub>TCCW</sub>	-	62	-	mA	RL=100Ω,CL=5pF V <sub>DD</sub> =3.3V,RS=V <sub>DD</sub> Worst Case pattern	f=85MHz
		-	45	-	mA	RL=100Ω,CL=5pF V <sub>DD</sub> =3.3V,RS=GND Worst Case pattern	f=85MHz
Transmitter Power Down Supply Current	I <sub>TCCS</sub>	-	-	10	μA	XRST=L	



Gray Scale Pattern

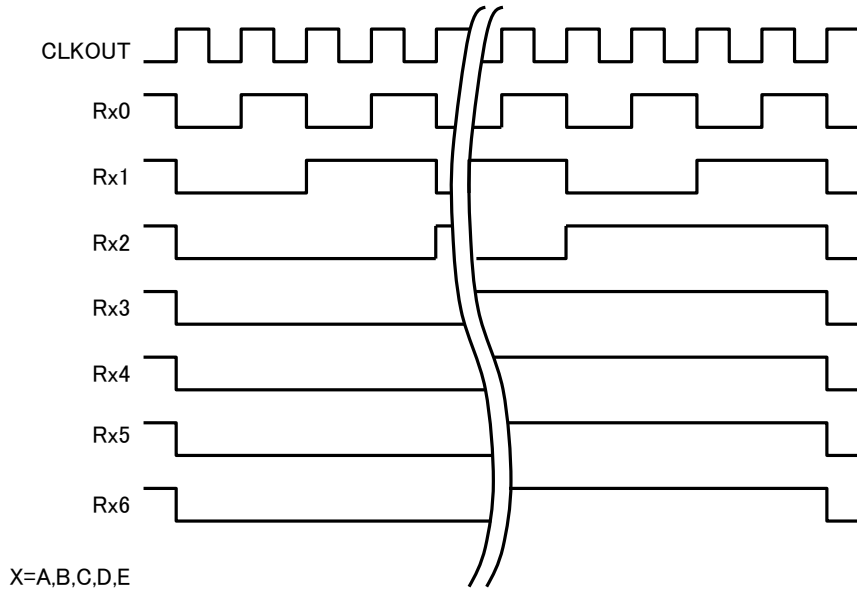


Fig.4 Gray scale pattern

Worst Case Pattern (Maximum Power condition)

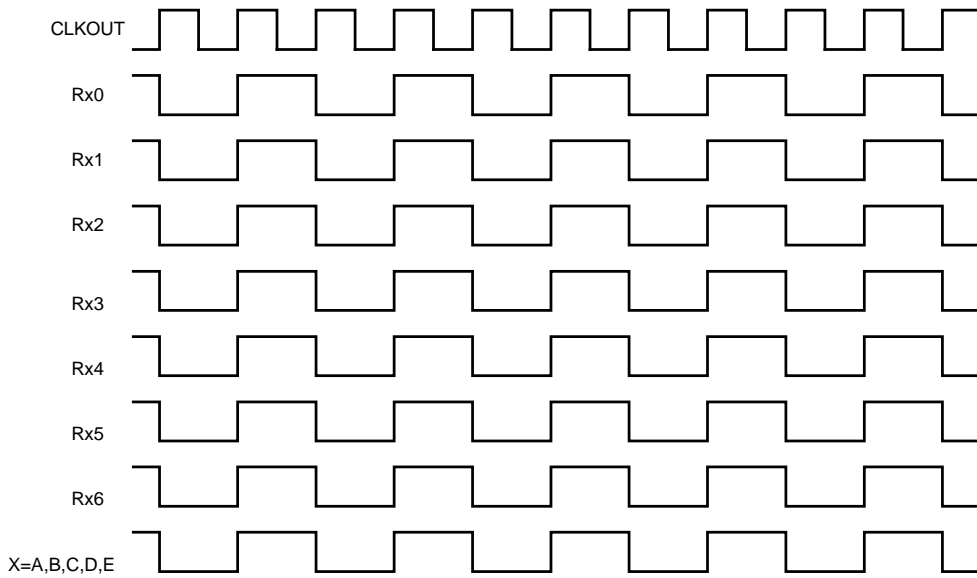


Fig.5 Worst Case Pattern

### ■ AC characteristics

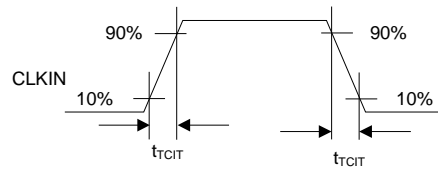
Table 8 : Switching Characteristics

Parameter	Symbol	Min	Typ	Max	Units
CLK IN Transition time	$t_{TCIT}$	-	-	5.0	ns
CLK IN Period	$t_{TCP}$	8.93	-	125.0	ns
CLK IN High Time	$t_{TCH}$	$0.35t_{TCP}$	$0.5t_{TCP}$	$0.65t_{TCP}$	ns
CLK IN Low Time	$t_{TCL}$	$0.35t_{TCP}$	$0.5t_{TCP}$	$0.65t_{TCP}$	ns
CLK IN to TCLK+/-Delay	$t_{TCD}$	-	$t_{TCP}$	-	ns
LVS MOS Data Set up to CLK IN	$t_{TS}$	2.5	-	-	ns
LVC MOS Data Hold from CLK IN	$t_{TH}$	0	-	-	ns
LVDS Transition Time	$t_{LVT}$	-	0.6	1.5	ns
Output Data Position 0	$t_{TOP1}$	-0.2	0.0	+0.2	ns
Output Data Position 1	$t_{TOP0}$	$\frac{t_{TCP}}{7} - 0.2$	$\frac{t_{TCP}}{7}$	$\frac{t_{TCP}}{7} + 0.2$	ns
Output Data Position 2	$t_{TOP6}$	$2 \frac{t_{TCP}}{7} - 0.2$	$2 \frac{t_{TCP}}{7}$	$2 \frac{t_{TCP}}{7} + 0.2$	ns
Output Data Position 3	$t_{TOP5}$	$3 \frac{t_{TCP}}{7} - 0.2$	$3 \frac{t_{TCP}}{7}$	$3 \frac{t_{TCP}}{7} + 0.2$	ns
Output Data Position 4	$t_{TOP4}$	$4 \frac{t_{TCP}}{7} - 0.2$	$4 \frac{t_{TCP}}{7}$	$4 \frac{t_{TCP}}{7} + 0.2$	ns
Output Data Position 5	$t_{TOP3}$	$5 \frac{t_{TCP}}{7} - 0.2$	$5 \frac{t_{TCP}}{7}$	$5 \frac{t_{TCP}}{7} + 0.2$	ns
Output Data Position 6	$t_{TOP2}$	$6 \frac{t_{TCP}}{7} - 0.2$	$6 \frac{t_{TCP}}{7}$	$6 \frac{t_{TCP}}{7} + 0.2$	ns
Phase Locked Loop Set Time	$t_{TPLL}$	-	-	10.0	ms

● AC Timing

■ AC Timing Diagrams

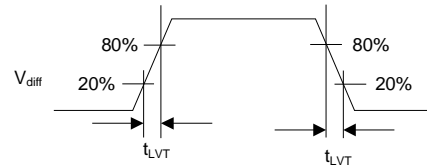
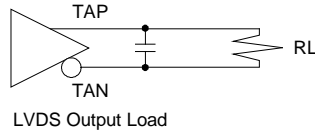
LVC MOS Input



LVC MOS Output

LVDS Output

$$V_{diff} = (TAP) - (TAN)$$



LVC MOS Input

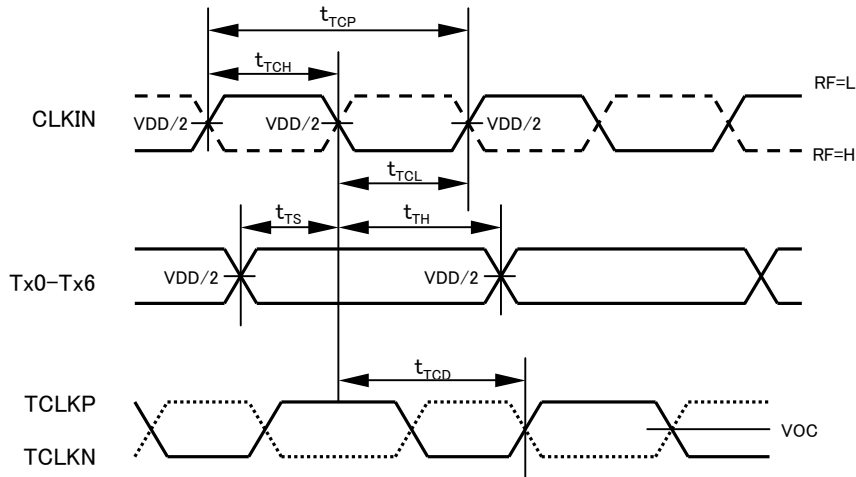


Fig.6 AC Timing Diagrams

■ Small Swing Inputs

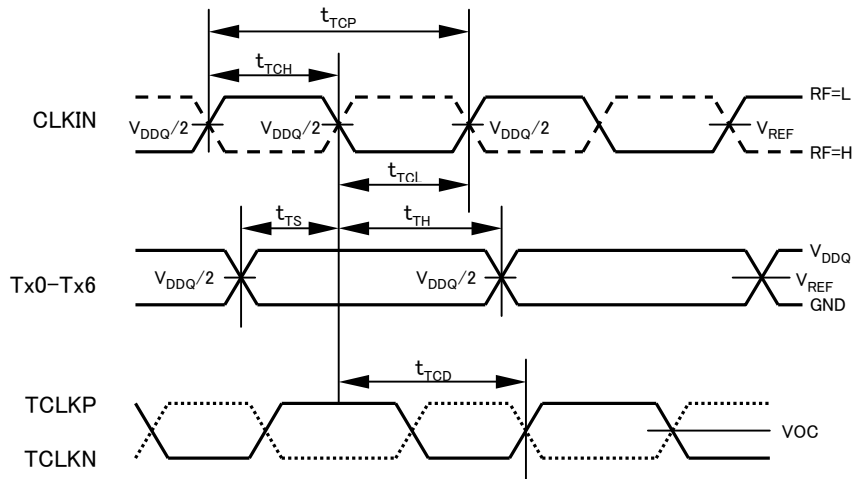


Fig.7 Small Swing Inputs

■ AC Timing Diagrams

LVDS Output

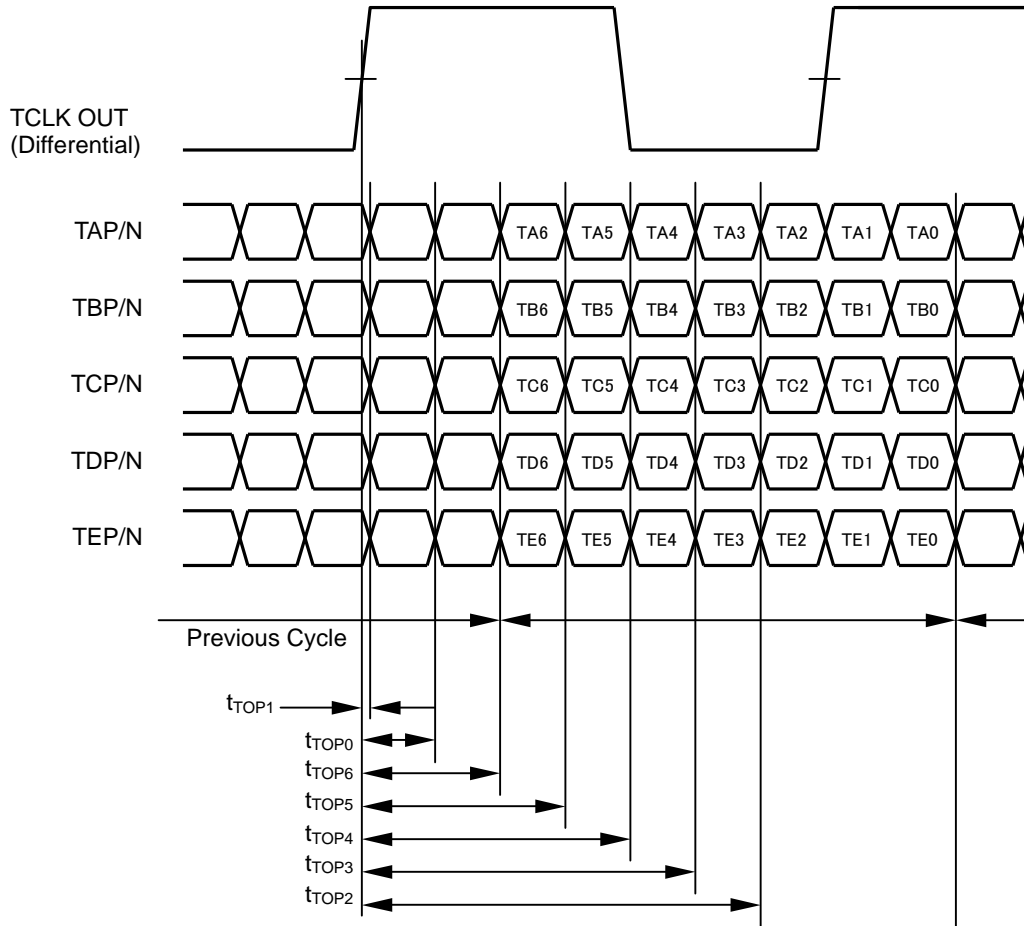


Fig.8 AC Timing Diagrams

■ Phase Locked Loop Set Time

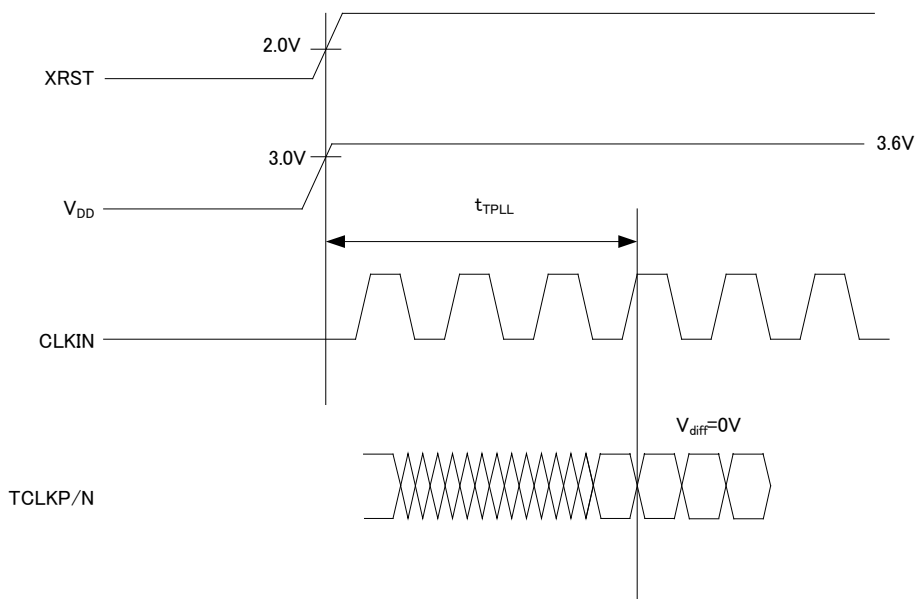


Fig.9 Phase Locked Loop Set Time

●System Timing Requirement

System Timing Requirement is mandatory by following two methods.

- ①The method of using CR circuit.( In the case that CLK does not stop after power supply)
- ② The method of using external specific IC. (In the case that CLK turns on/off after power supply)

It is recommend to do enough examination for target application.

- ① The method of using CR circuit.( In the case that CLK does not stop after power supply)

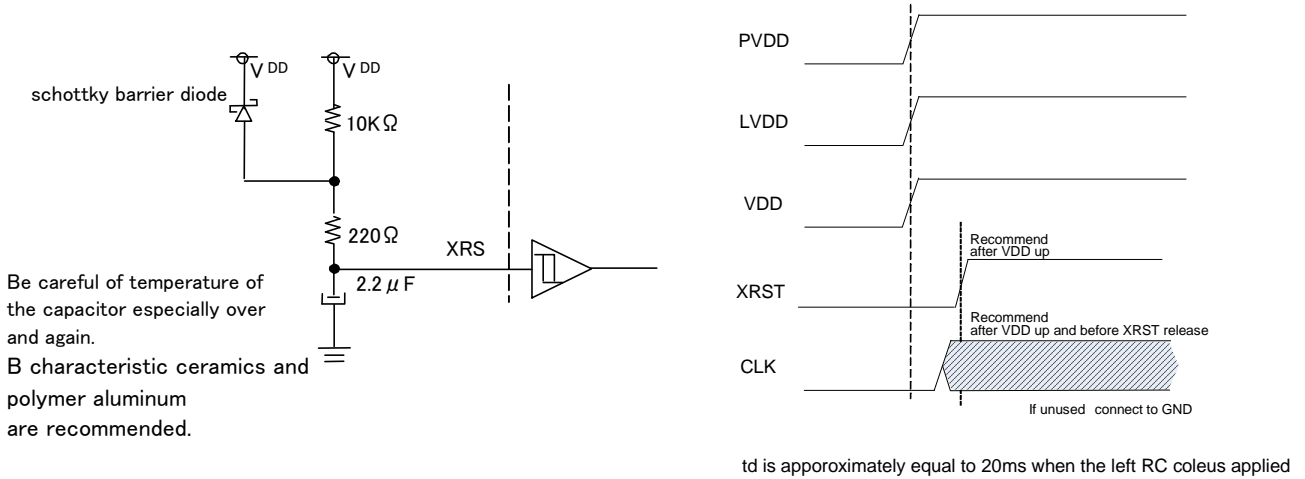


Fig.10 The method of using CR circuit

- ②The method of using external specific IC. (In the case that CLK turns on/off after power supply)

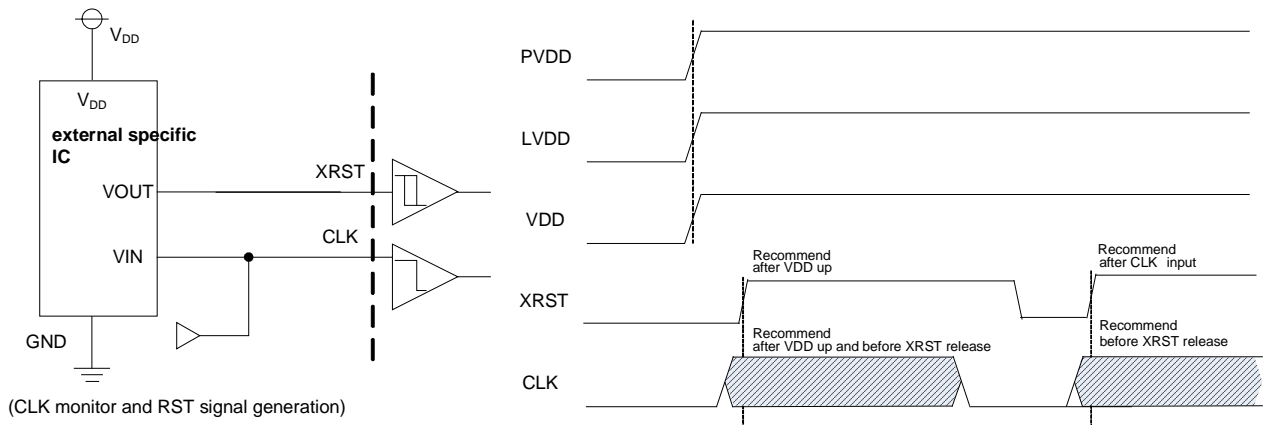
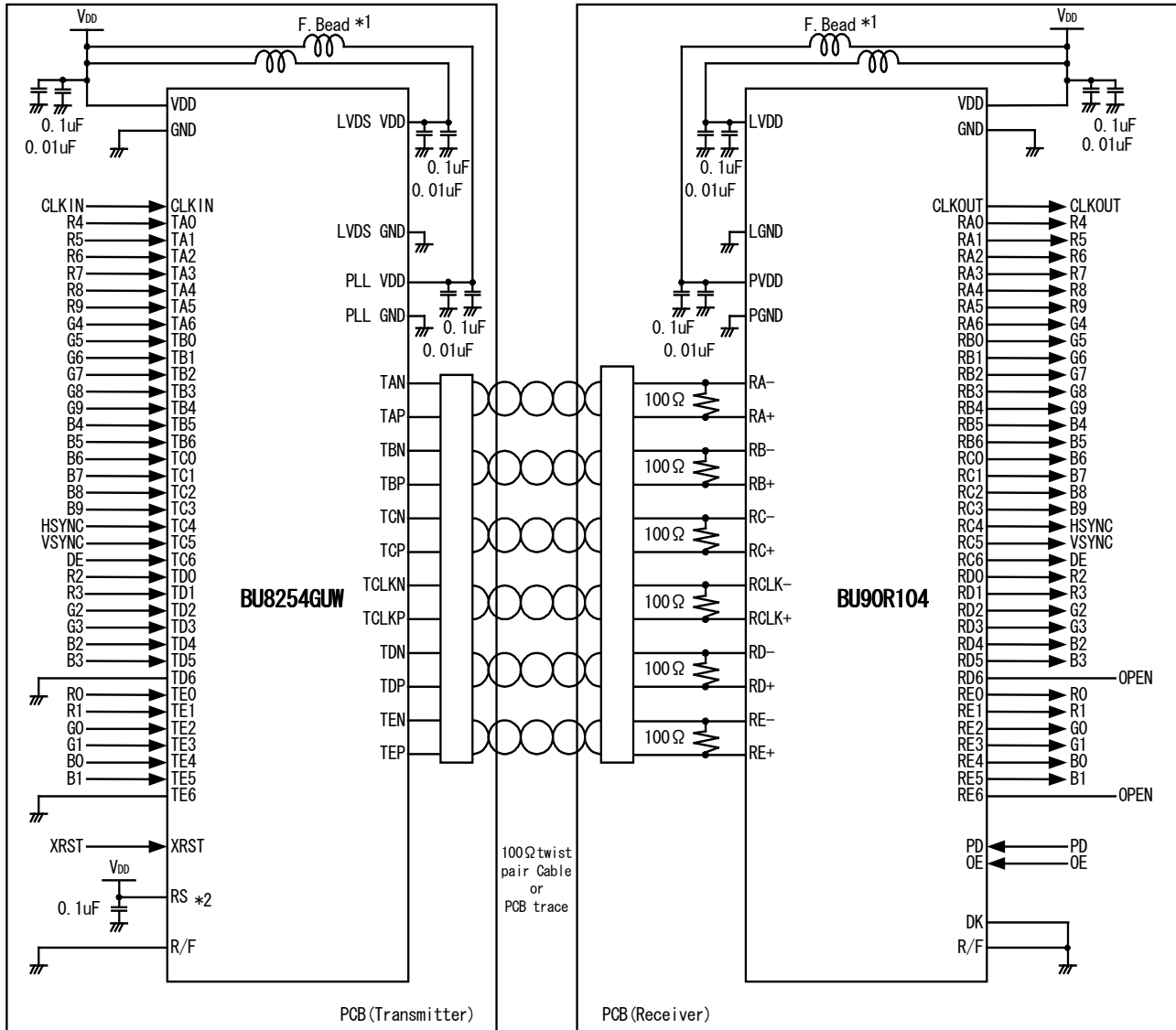


Fig.11 The method of using external specific IC.

●10bit LVCMOS Level Input

Example:  
 BU8254GUW : LVCMOS level input/Falling edge/Normal swing  
 BU90R104 : Falling edge

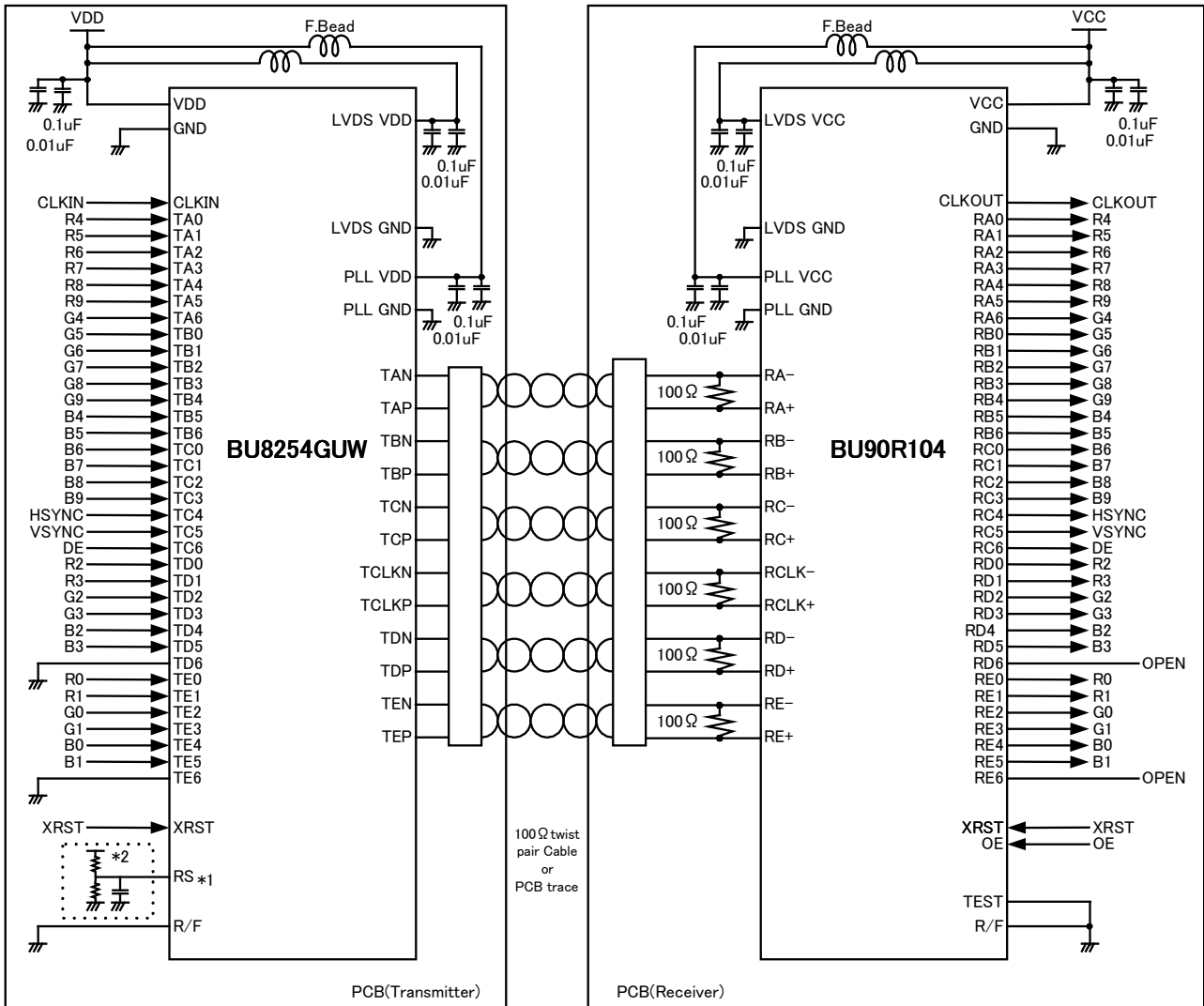


\*1 : Recommended Parts:  
 F.Bead : BLM18A-Series (Murata Manufacturing)

\*2 : If RS pin is tied to V<sub>DD</sub>, LVDS swing is 350m V.  
 If RS pin is tied to GND, LVDS swing is 200m V.

●10bit Small Swing Input

Example:  
 BU8254GUW : LVCMOS level input/Falling edge/Normal swing  
 BU90R104 : Falling edge



- \*3 : Recommended Parts:  
 F.Bead : BLM18A-Series (Murata Manufacturing)
- \*4 : RS pin acts as VREF input pin when input voltage is set to half of high level signal input.  
 We recommend to locate by-pass condenser near the RS pin.

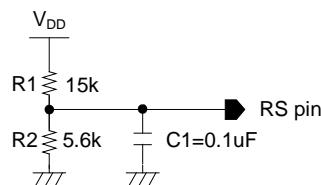
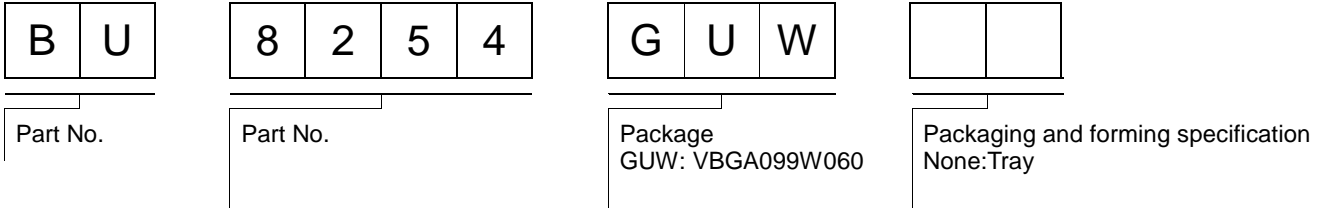


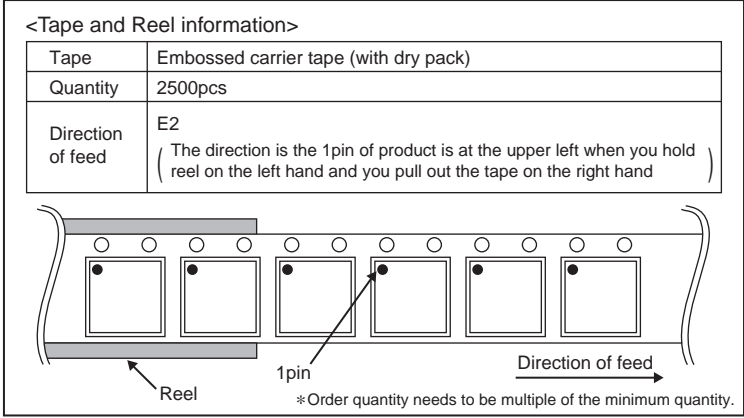
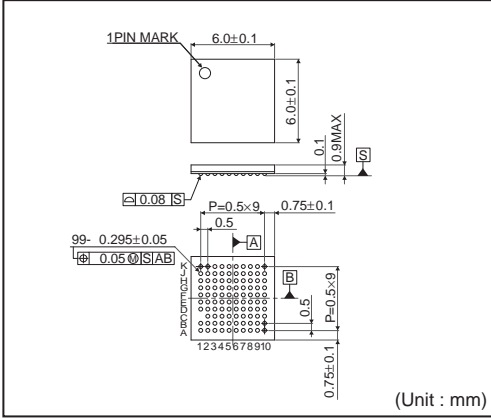
Fig.12 Example for LVCMOS(1.8V input)(R1,R2)=(1.5kΩ,5.6kΩ)



● Ordering Part Number



**VBGA099W060**



# Notice

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

- ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
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  - Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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  - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - Sealing or coating our Products with resin or other coating materials
  - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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**Precaution for Electrostatic**

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**Precaution for Storage / Transportation**

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

**Precaution for Product Label**

QR code printed on ROHM Products label is for ROHM's internal use only.

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When disposing Products please dispose them properly using an authorized industry waste company.

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